

封裝設備 (PECVD)

OLED 中的有機半導體材料及低功函數電極極易受氧氣與水氣影響，因此 OLED 元件的使用壽命是一大挑戰，必須利用有效的封裝技術來阻絕水氣與氧氣的侵入，才能達到足夠的元件穩定性。

CHAMBER	Electrolytic Polishing SUS304 + Anodizing AL
Plasma Type	Inductively coupled plasma (ICP)
RF Power	1500W@13.56MHz
Substrate Temperature	<80°C
Substrate Size	up to 100mm square or 4"
Base Pressure	< 3X10 ⁻⁷ Torr
Process Pressure Range	0.002 to 2 Torr
Pumping System	Dry + CRYO Pump
APC System	BG+Throttle Valve+Controller
Vacuum Gauge	CGX3 ; IGX1
Load/Unload (Option)	Vacuum Robot Transport
Load-Locks Pumping System (Option)	Dry Pump
Automatic Control System	PC+PLC
Uniformity	< +/- 2.5% @300nm
Power Requirement	AC220V/3 phase/60 Hz/125A
N ₂ Requirement	5kgw/cm ²
CDA Requirement	7kgw/cm ²
Water Requirement	3kgw/cm ²
Dimension (WxDxH)	1200mmX930mmX2400mm
Weight	726kgw